

August 2014

FCH110N65F

N-Channel SuperFET[®] II FRFET[®] MOSFET 650 V, 35 A, 110 m Ω

Features

- 700 V @ T_J = 150°C
- Typ. $R_{DS(on)} = 96 \text{ m}\Omega \text{ (Typ.)}$
- Ultra Low Gate Charge (Typ. Q_q = 98 nC)
- Low Effective Output Capacitance (Typ. C_{oss(eff.)} = 464 pF)
- · 100% Avalanche Tested
- · RoHS Compliant

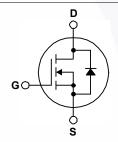
Applications

- LCD / LED / PDP TV Telecom / Server Power Supplies
- · Solar Inverter
- AC DC Power Supply

Description

SuperFET® II MOSFET is Fairchild Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently, SuperFET II MOSFET is very suitable for the switching power applications such as PFC, server/telecom power, FPD TV power, ATX power and industrial power applications. SuperFET II FRFET® MOSFET's optimized body diode reverse recovery performance can remove additional component and improve system reliability.





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol		Parameter		FCH110N65F_F155	Unit	
V _{DSS}	Drain to Source Voltage			650	V	
V	Gate to Source Voltage	- DC		±20	V	
V_{GSS}	GSS Gate to Source voltage	- AC	(f > 1 Hz)	±30	V	
	Drain Current	- Continuous (T _C = 25°C)		35	Α	
'D	Drain Current	- Continuous (T _C = 100°C)		24	A	
I _{DM}	Drain Current	- Pulsed (Note 1)		105	Α	
E _{AS}	Single Pulsed Avalanche Energy (Note 2)			809	mJ	
I _{AR}	Avalanche Current	Avalanche Current (Note 1)		8	Α	
E _{AR}	Repetitive Avalanche Energy	Repetitive Avalanche Energy (Note 1)			mJ	
dv/dt	MOSFET dv/dt			100	V/ns	
uv/ut	Peak Diode Recovery dv/dt		(Note 3)	50	V/IIS	
D	Dayyar Dissipation	(T _C = 25°C)		357	W	
P_{D}	Power Dissipation	- Derate Above 25°C		2.86	W/°C	
T _J , T _{STG}	Operating and Storage Temperatu	ure Range		-55 to +150	٥С	
T _L	Maximum Lead Temperature for \$ 1/8" from Case for 5 Seconds	Soldering,		300	°C	

Thermal Characteristics

Symbol	Parameter FCH110N65F_F155			
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max. 0.35			
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max. 40			

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCH110N65F_F155	FCH110N65F	TO-247G03	Tube	N/A	N/A	30 units

Test Conditions

Min.

Тур.

Max.

Unit

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted. Parameter

Off Chara	acteristics					
D\/	BV _{DSS} Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 10 \text{ mA}, T_J = 25^{\circ}\text{C}$	650	-	-	V
BV _{DSS} Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 10 \text{ mA}, T_J = 150^{\circ}\text{C}$	700	-	-	, v	
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 10 mA, Referenced to 25°C	-	0.67	-	V/°C
	Zero Gate Voltage Drain Current	V _{DS} = 650 V, V _{GS} = 0 V	-	-	10	
I _{DSS} Zero Gate voltage Drain Current	$V_{DS} = 520 \text{ V}, T_{C} = 125^{\circ}\text{C}$	-	110	-	μА	
I _{GSS}	Gate to Body Leakage Current	V _{GS} = ±20 V, V _{DS} = 0 V	-	-	±100	nA

On Characteristics

Symbol

V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 3.5 \text{ mA}$	3	-	5	V
R _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 17.5 \text{ A}$	-	96	110	mΩ
9 _{FS}	Forward Transconductance	V _{DS} = 20 V, I _D = 17.5 A	-	30	1	S

Dynamic Characteristics

C _{iss}	Input Capacitance		V - 400 V V - 0 V	-	3680	4895	pF
C _{oss}	Output Capacitance	V _{DS} = 100 V, V _{GS} = 0 V, f = 1 MHz		-	110	145	pF
C _{rss}	Reverse Transfer Capacitance			-	0.65	-	pF
C _{oss}	Output Capacitance		$V_{DS} = 380 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	65	-	pF
C _{oss(eff.)}	Effective Output Capacitance		V _{DS} = 0 V to 400 V, V _{GS} = 0 V	-	464	-	pF
Q _{g(tot)}	Total Gate Charge at 10V		V _{DS} = 380 V, I _D = 17.5 A,	-	98	145	nC
Q_{gs}	Gate to Source Gate Charge		V _{GS} = 10 V	-	20	-	nC
Q_{gd}	Gate to Drain "Miller" Charge		(Note 4)	-	43	-	nC
ESR	Equivalent Series Resistance		f = 1 MHz	-	0.7	-	Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time		-	31	72	ns
t _r	Turn-On Rise Time	$V_{DD} = 380 \text{ V}, I_{D} = 17.5 \text{ A},$	-/	21	52	ns
t _{d(off)}	Turn-Off Delay Time	V_{GS} = 10 V, R_g = 4.7 Ω	-	89	188	ns
t _f	Turn-Off Fall Time	(Note 4	-	5.7	21	ns

Drain-Source Diode Characteristics

Is	Maximum Continuous Drain to Source Diode Forward Current			-	35	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current			-	105	Α
V_{SD}	Drain to Source Diode Forward Voltage V _{GS} = 0 V, I _{SD} = 17.5 A		-	-	1.2	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _{SD} = 17.5 A,	-	133	-	ns
Q _{rr}	Reverse Recovery Charge dI _F /dt = 100 A/μs		-	0.67	-	μC

- 1. Repetitive rating: pulse width limited by maximum junction temperature.
- 2. I_{AS} = 8 A, R_G = 25 Ω , starting T_J = 25°C.
- 3. I $_{SD} \leq$ 17.5 A, di/dt \leq 200 A/µs, V $_{DD} \leq$ 380 V, starting T $_{J}$ = 25°C.
- 4. Essentially independent of operating temperature typical characteristics.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

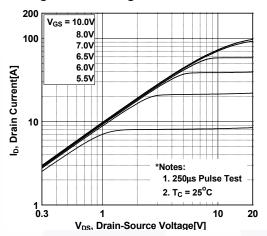


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

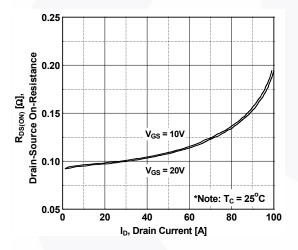


Figure 5. Capacitance Characteristics

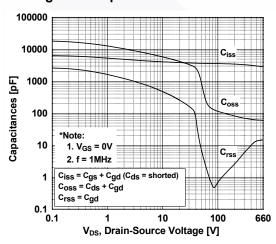


Figure 2. Transfer Characteristics

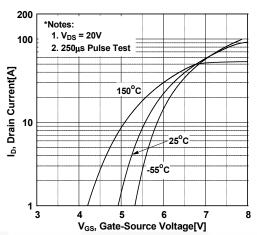


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

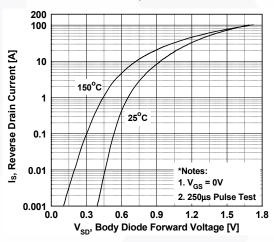
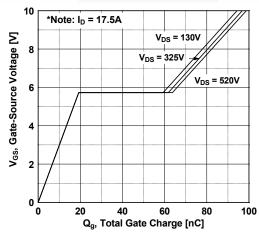


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

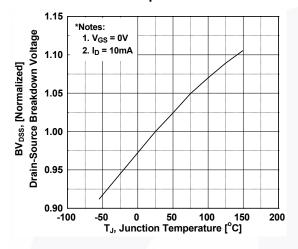


Figure 9. Maximum Safe Operating Area

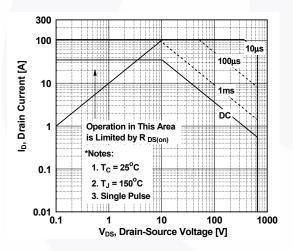


Figure 11. Eoss vs. Drain to Source Voltage

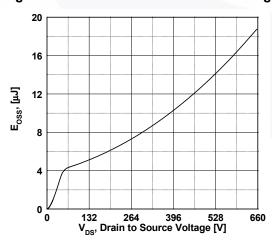


Figure 8. On-Resistance Variation vs. Temperature

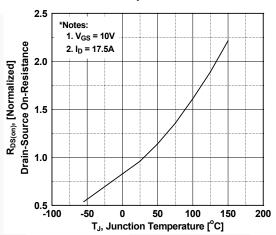
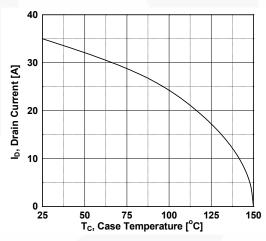
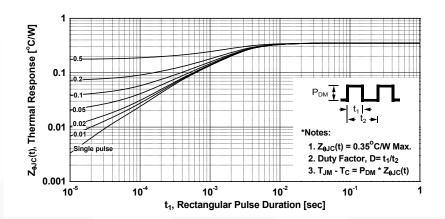


Figure 10. Maximum Drain Current vs. Case Temperature



Typical Performance Characteristics (Continued)

Figure 12. Transient Thermal Response Curve



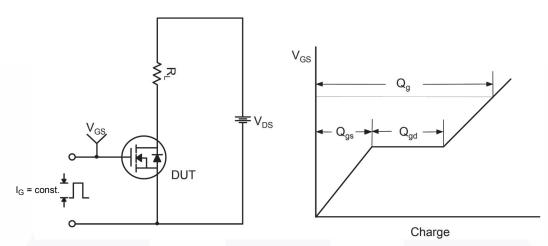


Figure 13. Gate Charge Test Circuit & Waveform

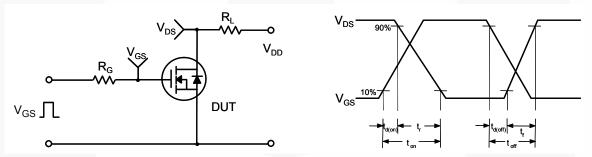


Figure 14. Resistive Switching Test Circuit & Waveforms

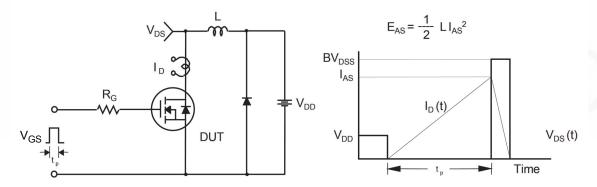


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

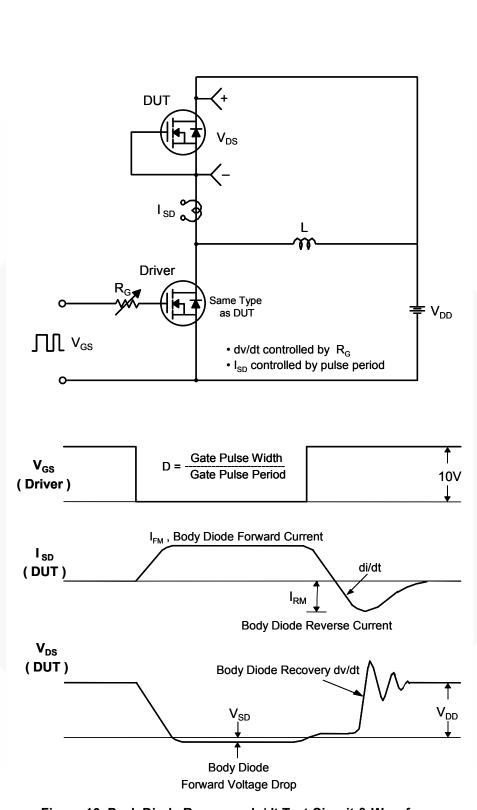
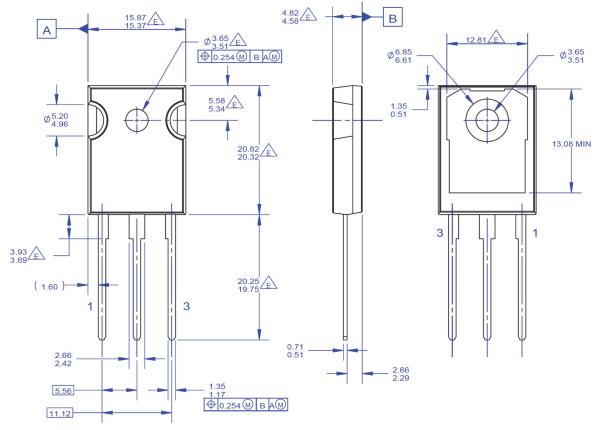


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms

Mechanical Dimensions



- NOTES: UNLESS OTHERWISE SPECIFIED
- A. PACKAGE REFERENCE: JEDEC TO-247,
- ISSUE E, VARIATION AB, DATED JUNE, 2004. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- ALL DIMENSIONS ARE IN MILLIMETERS.
 DRAWING CONFORMS TO ASME Y14.5 1994
- DOES NOT COMPLY JEDEC STANDARD VALUE
 F. DRAWING FILENAME: MKT-TO247G03_REV01

Figure 17. TO-247, Molded, 3-Lead, Jedec AB Long Leads

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